

# SOT1363-1

WFBGA171: plastic very-very-thin profile fine-pitch ball grid array package; 171 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WFBGA171
<b>Package type industry code</b>	WFBGA171
<b>Package style descriptive code</b>	WFBGA (very-very-thin profile fine-pitch ball grid array package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-4-2014

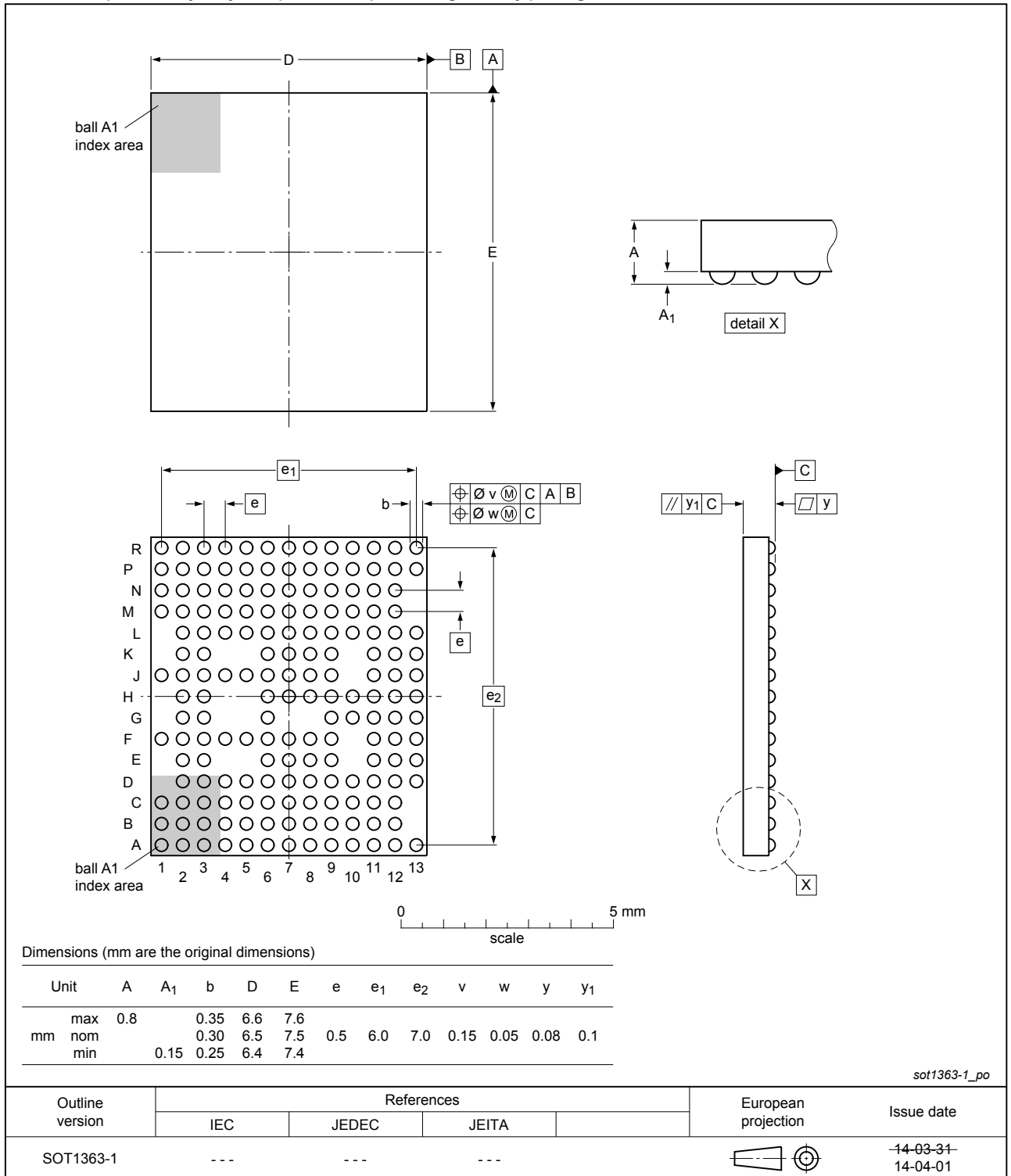
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.4	-	6.5	6.6	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	[tbd]	0.8	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	171	-	



## 2. Package outline

WFBGA171: plastic very-very-thin profile fine-pitch ball grid array package; 171 balls SOT1363-1



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Fig. 1. Package outline WFBGA171 (SOT1363-1)

### 3. Legal information

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